

(1,27 mm) .050"

FCF, EMF SERIES

# FLEXCARD™ TERMINAL & SOCKET STRIPS

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?FCF](http://www.samtec.com?FCF) or [www.samtec.com?EMF](http://www.samtec.com?EMF)

**Insulator Material:**  
Black Liquid Crystal Polymer

**Terminal Material (FCF):**  
Phosphor Bronze

**Contact Material (EMF):**  
BeCu

**Plating:**

Sn or Au over  
50µ" (1,27 µm) Ni

**Operating Temp Range:**  
FCF = -55°C to +105°C Tin  
FCF = -55°C to +125°C Gold  
EMF = -55°C to +125°C

**Contact Resistance (EMF):**  
10 mΩ

**Insertion Depth (EMF):**  
(3,05 mm) .120" to  
(4,06 mm) .160"

**Insertion Force (EMF):**  
(Single contact only)  
3.0 oz (0,83 N) avg.

**Withdrawal Force (EMF):**  
(Single contact only)  
2.0 oz (0,56 N) avg.

**Lead-Free Solderable:**  
Yes

**SMT Lead Coplanarity (EMF):**  
(0,10 mm) .004" max (20)  
(0,15 mm) .006" max (30-50)

**RoHS Compliant:**  
Yes



Mates with: EMF

20, 30, 40 & 50  
(Standard sizes)

Specify  
LEAD  
STYLE  
from  
chart

PLATING  
OPTION

-L  
= 10µ" (0,25 µm)  
Gold on post,  
Matte Tin on tail

-S  
= 30µ" (0,76 µm)  
Gold on post,  
Matte Tin on tail

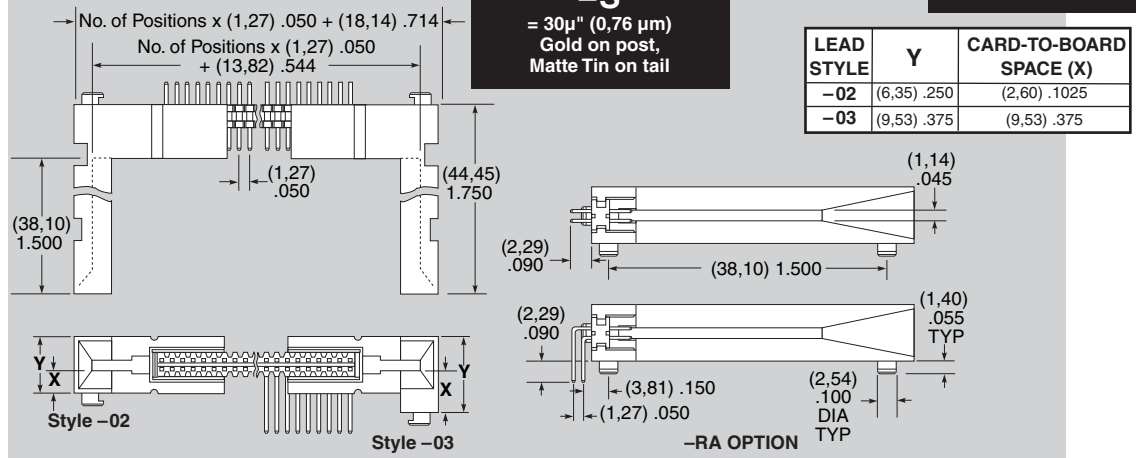
CARD  
SLOT

-01  
= Accepts  
(0,80 mm)  
.031"  
thick  
card

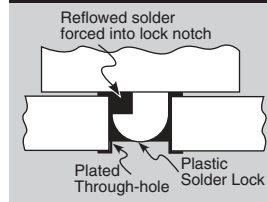
TAIL  
OPTION

-RA  
= Right Angle  
(Leave blank for  
vertical version.  
Style -02 only)

SL



## APPLICATIONS



## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



Mates with: FCF

20, 30, 40 & 50  
(Standard sizes)

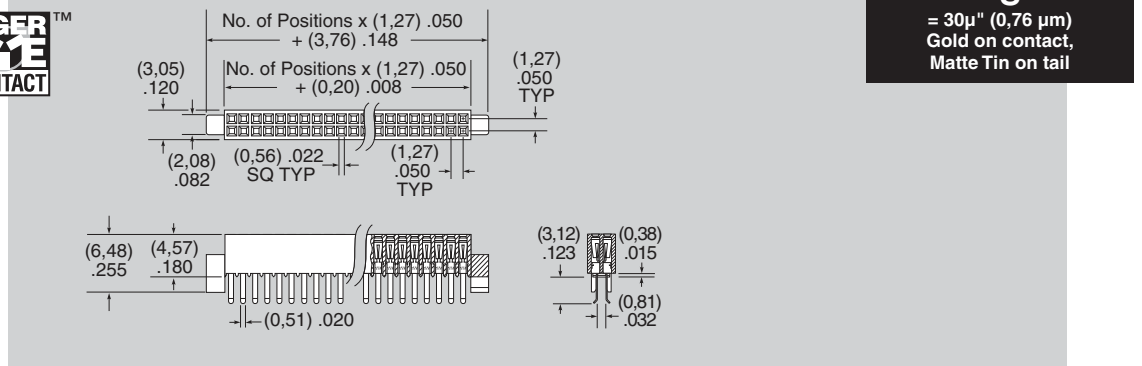
-01  
= (0,80 mm) .031"  
thick board

PLATING  
OPTION

-L  
= 10µ" (0,25 µm)  
Gold on contact,  
Matte Tin on tail

-S  
= 30µ" (0,76 µm)  
Gold on contact,  
Matte Tin on tail

D



**Note:** Some lengths, styles and options are non-standard, non-returnable.